

Features

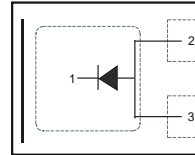
- Ultra Low Forward Voltage Drop
- Excellent High Temperature Stability
- Patented Super Barrier Rectifier Technology
- Soft, Fast Switching Capability
- 150°C Operating Junction Temperature
- **Lead Free By Design, RoHS Compliant (Note 1)**
- **“Green” Molding Compound (No Br, Sb)**



Top View



Bottom View


 Top View
Internal Schematic

Mechanical Data

- Case: DFN1411-3
- Case Material: Molded Plastic, “Green” Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminal Connections: See Diagram
- Terminals: Finish – NiPdAu over Copper Lead Frame. Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 3
- Ordering Information: See Page 3
- Weight: 2.35mg (approximate)

Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	40	V
Working Peak Reverse Voltage	V_{RWM}		
DC Blocking Voltage	V_{RM}		
RMS Reverse Voltage	$V_{R(RMS)}$	28	V
Average Rectified Output Current (See Figure 1)	I_O	1.0	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I_{FSM}	5	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Maximum Thermal Resistance			$^\circ\text{C}/\text{W}$
Thermal Resistance Junction to Ambient (Note 2)	$R_{\theta JA}$	190	$^\circ\text{C}/\text{W}$
Operating and Storage Temperature Range	T_J, T_{STG}	-65 to +150	$^\circ\text{C}$

Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 3)	$V_{(BR)R}$	40	-	-	V	$I_R = 100\mu\text{A}$
Forward Voltage Drop	V_F	-	0.39	0.42	V	$I_F = 0.5\text{A}, T_J = 25^\circ\text{C}$
		-	0.46	0.49		$I_F = 1.0\text{A}, T_J = 25^\circ\text{C}$
		-	0.34	0.37		$I_F = 0.5\text{A}, T_J = 125^\circ\text{C}$
		-	0.43	0.47		$I_F = 1.0\text{A}, T_J = 125^\circ\text{C}$
Leakage Current (Note 3)	I_R	-	-	50	μA	$V_R = 40\text{V}, T_J = 25^\circ\text{C}$
				100	mA	$V_R = 40\text{V}, T_J = 125^\circ\text{C}$

- Notes:
1. No purposefully added lead.
 2. Device mounted on Polyimide substrate 1" x 1", 2oz. Copper double sided PCB board.
 3. Short duration pulse test used to minimize self-heating effect.

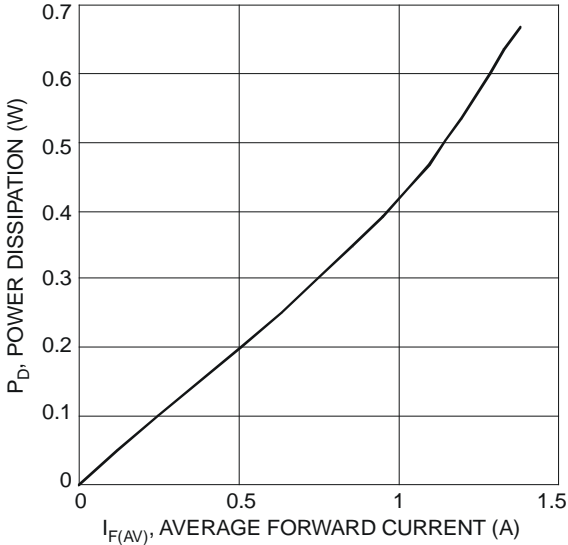


Fig. 1 Forward Power Dissipation

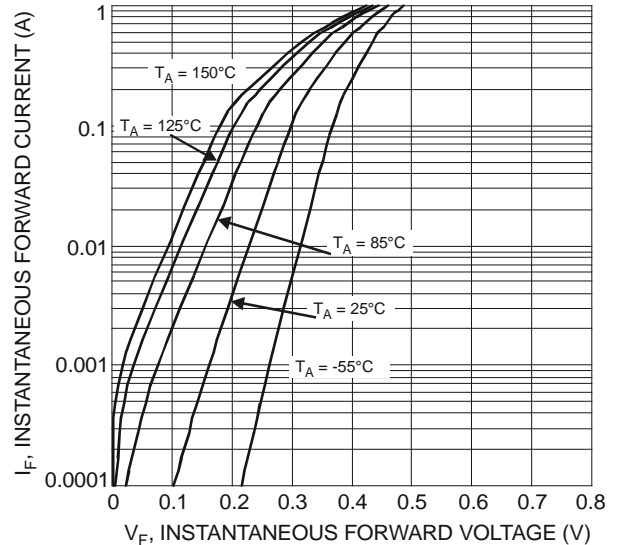


Fig. 2 Typical Forward Characteristics

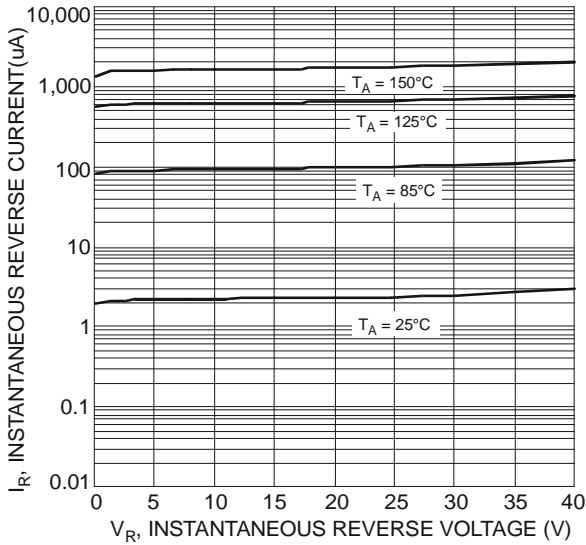


Fig. 3 Typical Reverse Characteristics

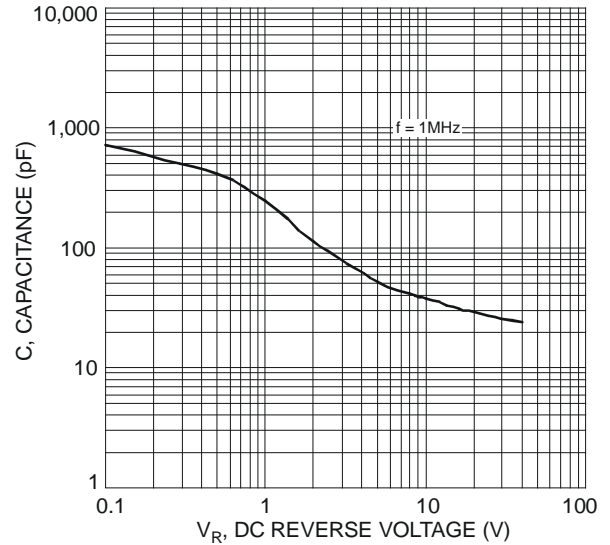


Fig. 4 Total Capacitance vs. Reverse Voltage

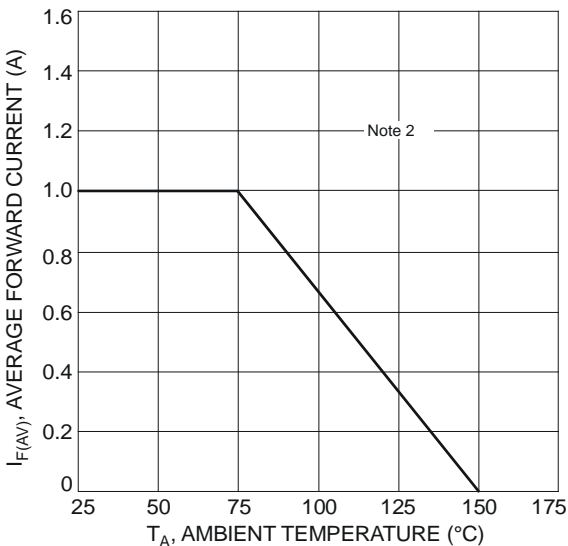


Fig. 5 Forward Current Derating Curve

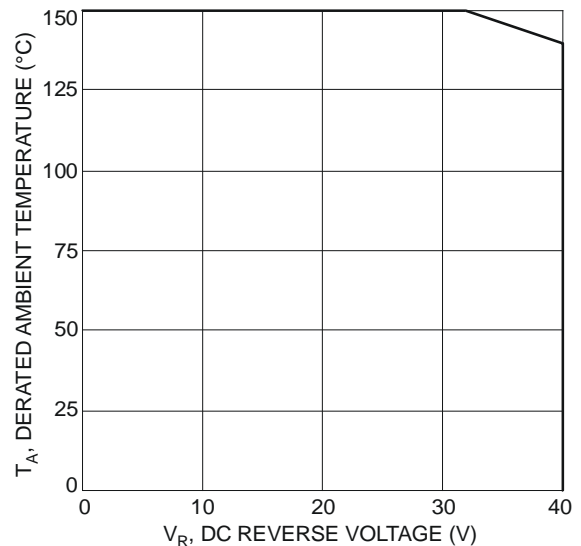
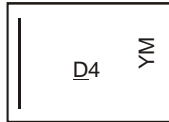


Fig. 6 Operating Temperature Derating

Ordering Information (Note 4)

Part Number	Case	Packaging
SBR1U40LP-7	DFN1411-3	3000/Tape & Reel

Notes: 4. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

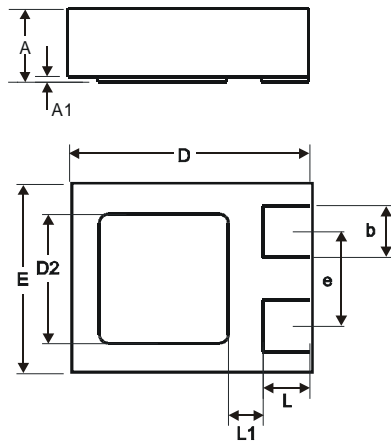
Marking Information


D4 = Product Type Marking Code
 YM = Date Code Marking
 Y = Year ex: U = 2007
 M = Month (ex: 9 = September)

Date Code Key

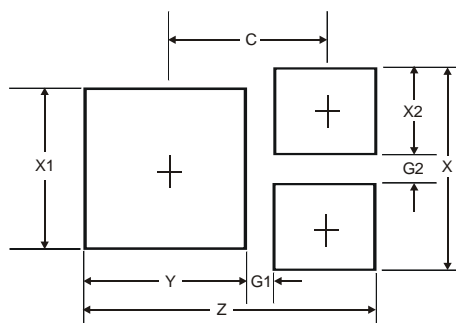
Year	2007	2008	2009	2010	2011	2012	2013	2014	2015
Code	U	V	W	X	Y	Z	A	B	C

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Package Outline Dimensions


DFN1411-3			
Dim	Min	Max	Typ
A	0.47	0.53	0.50
A1	0	0.05	0.02
b	0.25	0.35	0.30
D	1.35	1.475	1.40
D2	0.65	0.85	0.75
E	1.05	1.18	1.10
e	—	—	0.55
L	0.225	0.325	0.275
L1	—	—	0.20

All Dimensions in mm

Suggested Pad Layout


Dimensions	Value (in mm)
Z	1.38
G1	0.15
G2	0.15
X	0.95
X1	0.75
X2	0.40
Y	0.75
C	0.76

IMPORTANT NOTICE

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to any product herein. Diodes Incorporated does not assume any liability arising out of the application or use of any product described herein; neither does it convey any license under its patent rights, nor the rights of others. The user of products in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on our website, harmless against all damages.

LIFE SUPPORT

Diodes Incorporated products are not authorized for use as critical components in life support devices or systems without the expressed written approval of the President of Diodes Incorporated.